Product/Process Change Notice - PCN 14_0177 Rev. -

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Material Report). Any issues with this PCN or requirements to qualify the change (additional data or samples) must be sent to ADI within 30 days of publication date. ADI contact information is listed below.

PCN Title:	Conversion of 6x6mm LFCSP Package Outlines from Punch to Sawn and Transfer of Assembly Site to Amkor Philippines
Publication Date:	10-Sep-2014
Effectivity Date:	09-Dec-2014 *(the earliest date that a customer could expect to receive changed material)*

Revision Description:

Initial Release

Description Of Change

ADI has qualified and will be utilizing Assembly subcontractor Amkor in the Philippines for 6x6mm body sizes LFCSP products. ADI has also qualified Amkor's standard bill of materials in a SAWN singulated leadframe. There will be change in BOM for Die Attach Epoxy from Alblestik 8290 to Ablestik 3230. Pin1 indicator will be laser marked as part of the change. See attached for changes and package outline differences.

Reason For Change

Sawn LFCSP is ADI's technology direction for LFCSP. The use of ADI qualified Amkor-Philippines as an assembly site will ensure continued source of product supply. ADI's assembly subcontractors manufacture our products using Analog Devices specified manufacturing flows, process controls and monitors. This assures that our customers receive the same level of quality and reliability on products they receive from qualified ADI manufacturing locations.

Impact of the change (positive or negative) on fit, form, function & reliability

The devices function and reliability as specified by the product datasheet will be unaffected by these changes. The Lead Foot Print Dimension will remain the same for both punch and sawn LFCSP packages

Summary of Supporting Information

Qualification has been performed per AEC-Q100, Stress Test Qualification for Integrated Circuits. See attached Qualification Results Summary.

Supporting Documents

Attachment 1: Type: Qualification Results Summary

ADI_PCN_14_0177_Rev_-_Qualification Results Summary.pdf

Attachment 2: Type: Detailed Change Description

ADI_PCN_14_0177_Rev_-_BOM.xlsx

Attachment 3: Type: Package Outline Drawing

ADI_PCN_14_0177_Rev_-_Package Ouline Drawing.pdf

For questions on this PCN, send email to the regional contacts below or contact your local ADI sales representative					
Americas:	PCN_Americas@analog.com	**Europe:**	PCN_Europe@analog.com	**Japan:** **Rest of Asia:**	PCN_Japan@analog.com PCN_ROA@analog.com

Appendix A - Affected ADI Models

Added Parts On This Revision - Product Family / Model Number (14)

ADV7174 / ADV7174WBCPZ	ADV7174 / ADV7174WBCPZ-REEL	ADV7179 / ADV7179WBCPZ	ADV7179 / ADV7179WBCPZ-REEL	ADV7180 / ADV7180WBCPZ
ADV7180 / ADV7180WBCPZ-REEL	ADV7180 / ADW10003-0REEL	ADV7180 / ADW10006Z-0	ADV7180 / ADW10007Z-0	ADV7180 / ADW10007Z-0REEL
ADV7392 / ADV7392WBCPZ	ADV7392 / ADV7392WBCPZ-REEL	ADV7393 / ADV7393WBCPZ	ADV7393 / ADV7393WBCPZ-REEL	

Appendix B - Revision History			
Rev	**Publish Date**	**Effectivity Date**	**Rev Description**
Rev. -	10-Sep-2014	09-Dec-2014	Initial Release